

Listing of Claims

Claims ~~1-14~~ (Canceled)

Claim ~~15~~¹ (Currently amended) A method for depositing a solderable finish on an electronic device substrate, the method comprising;

electrolytically depositing onto the substrate a metal from an electroplating composition that comprises ~~at least one~~ one or more soluble metal salt, an electrolyte, at least ~~on one~~ one grain refiner/stabilizer additive comprising one or more ~~non-aromatic compounds having π electrons~~ that can be delocalized hydroxylated gamma-pyrone compounds.

Claim ~~16~~² (Original) The method of claim ~~15~~¹ wherein the metal salt comprises tin.

Claim ~~17~~ (Canceled)

Claim ~~18~~³ (Currently amended) The method of claim ~~15~~¹ wherein the grain refiner/stabilizer additive is present at ~~concentration-concentrations~~ of between about 2 mg and about 10,000 mg per liter of the electroplating composition.

Claim ~~19~~⁴ (Currently amended) The method of claim ~~15~~¹ wherein the stabilizer additive is present at ~~concentration-concentrations~~ of between about 50 mg and about 2000 mg per liter of the electroplating composition.

Claim ~~20~~⁵ (Original) The method of claim ~~15~~¹ further comprising a brightener agent.

Claim ~~21~~⁶ (Original) The method of claim ~~15~~¹ wherein the composition further comprises a suppressor agent.

Claim ~~22~~⁷ (Original) The method of claim ~~15~~¹ wherein the composition further comprises a leveler agent.

Claim ~~23~~⁸ (Original) The method of claim ~~15~~¹ wherein the substrate is a printed circuit board substrate or semiconductor with one or more microvias.

Claim ~~24~~⁹ (Original) The method of claim ~~15~~¹ wherein the substrate is a microchip module substrate.

Claim ~~25~~ (Canceled)

Claim ~~26~~ (Canceled)

Claim ~~27~~¹⁰ (New) The method of claim ~~15~~¹ wherein the hydroxylated gamma-pyrone comprises Kojic acid, meconic acid, comenic acid, maltol, or ethylmaltol.

~~11.~~
Claim ~~28~~ (New) The method of claim ~~15~~ wherein the soluble metal salt comprises a salt of tin, zinc, copper, nickel, gold, silver, bismuth, indium or antimony.

~~12.~~
Claim ~~29~~ (New) The method of claim ~~15~~ wherein the metal is a tin alloy.

~~13.~~
Claim ~~30~~ (New) The method of claim ~~29~~ wherein the tin alloy is an alloy of tin-silver or tin-copper.

~~14.~~
Claim ~~31~~ (New) the method of claim ~~15~~ wherein the metal is a zinc alloy.